

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STM32C031K6U3	73MG*453XXXZ	A	998Z	2023-06-06
Amount	UoM	Unit type	ST ECOPACK Grade	
48.59	mg	Each	ECOPACK® 2	
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used or other bulk termination : add in comments	Tin (Sn), immersion	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFN	5x5x0.55	32	flat	
Comment	Package : A0B8 UFQFPN 5X5X0.55 32L 0.5 MM PITCH 8202208			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-10 Jun 2022				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	73MG*453XXXZ				6000000.0	1000033.7				
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)				
Die or dies	M-011 Other inorganic materials	1.031	mg	supplier	die	Silicon (Si)	7440-21-3		0.931	mg	903007	19160				
				supplier	metallization	Aluminium (Al)	7429-90-5		0.005	mg	4850	103				
				supplier	metallization	Copper (Cu)	7440-50-8		0.042	mg	40737	864				
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.014	mg	13579	288				
				supplier	metallization	Titanium (Ti)	7440-32-6		0.001	mg	970	21				
				supplier	Passivation	Silicon Nitride	12033-89-5		0.011	mg	10669	226				
				supplier	Passivation	Silicon Oxide	7631-86-9		0.027	mg	26188	556				
				Supplier	Organic Compounds	Acrylic resin	Trade Secret		0.025	mg	70000	504				
				Supplier	Organic Compounds	Polybutadiene derivative	Trade Secret		0.007	mg	20000	144				
				Supplier	Organic Compounds	Butadiene copolymer	Trade Secret		0.005	mg	15000	108				
Glue epoxy (EN900GC)	M-011 Other inorganic materials	0.350	mg	Supplier	Organic Compounds	Acrylate	Trade Secret		0.019	mg	54000	389				
				Supplier	Organic Compounds	Epoxy resin	Trade Secret		0.011	mg	30000	216				
				Supplier	Organic Compounds	Peroxide	Trade Secret		0.003	mg	8000	58				
				Supplier	Organic Compounds	Additive	Trade Secret		0.006	mg	18000	130				
				Supplier	Metals	Silver	7440-22-4		0.275	mg	785000	5656				
				Encapsulation (EME-G770)	M-011 Other inorganic materials	17.779	mg	Supplier	Organic Compounds	Epoxy Resin A	Trade Secret		0.373	mg	21000	7684
								Supplier	Organic Compounds	Epoxy Resin B	Trade Secret		0.373	mg	21000	7684
								Supplier	Organic Compounds	Phenol Resin A	Trade Secret		0.373	mg	21000	7684
								Supplier	Glass	Silica(Amorphous)A	60676-86-0		13.876	mg	780450	285584
								Supplier	Glass	Silica(Amorphous)B	7631-86-9		2.050	mg	115320	42198
Supplier	Organic Compounds	Carbon Black	1333-86-4						0.111	mg	6230	2280				
Supplier	Metallic compounds	Metal Hydroxide	Trade Secret						0.249	mg	14000	5123				
Supplier	Organic Compounds	Phenol Resin B	Trade Secret						0.373	mg	21000	7684				
Bonding Wire (Au)	Bonding Wire	0.410	mg					Supplier	Metals	Gold	7440-57-5		0.410	mg	1000000	8443
Plating Anode (Sn)	M-011 Other inorganic materials	0.719	mg					Supplier	Metals	Tin	7440-31-5		0.719	mg	1000000	14796
Leadframe (C7025 + Ag)	Copper & its alloys	28.300	mg	Supplier	Metals	Copper	7440-50-8		25.955	mg	917140	534186				
				Supplier	Metals	Nickel	7440-02-0		0.637	mg	22500	13105				
				Supplier	Metals	Silicon	7440-21-3		0.074	mg	2600	1514				
				Supplier	Metals	Magnesium	7439-95-4		0.033	mg	1150	670				
				Supplier	Metals	Silver	7440-22-4		1.602	mg	56610	32972				